

Title (en)
TRANSLUCENT PANEL FOR CONNECTING ELECTRONIC COMPONENTS

Title (de)
DURCHSCHEINENDE PLATTE ZUR VERBINDUNG VON ELEKTRONISCHEN BAUTEILEN

Title (fr)
PANNEAU TRANSLUCIDE POUR CONNECTER DES COMPOSANTS ÉLECTRONIQUES

Publication
EP 2101996 A1 20090923 (FR)

Application
EP 07857761 A 20071218

Priority
• EP 2007064136 W 20071218
• EP 06126877 A 20061221
• EP 07857761 A 20071218

Abstract (en)
[origin: EP1935633A1] The method involves depositing a translucent electrically conductive base layer e.g. pyrolytic translucent layer disposed by liquid spray, on a translucent non colored clear glass substrate such as flat solid body. A part of a cover surface is temporarily masked by a conductive layer. A permanent insulating translucent layer is deposited on the cover layer. A temporary masking material and an insulating material are removed to provide a contact zone at sides of an insulating zone. A translucent conductive layer is deposited on the insulating zone to form another contact zone. The translucent electrically conductive base layer is made of silver and can be a pyrolytic translucent layer disposed by chemical vapor deposition (CVD) technique or a tin oxide layer doped with fluorine and/or antimony. An independent claim is also included for a translucent panel for connecting electronic components.

IPC 8 full level
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CPC (source: EP)
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